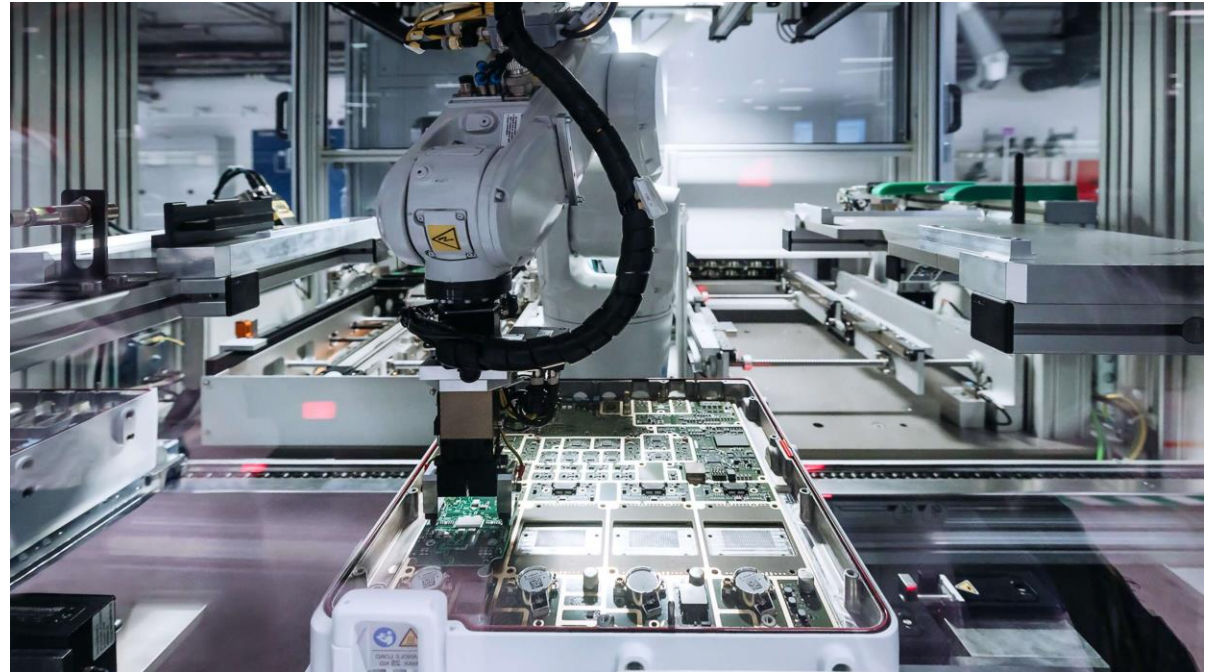


Simplified life cycle assessment methodology

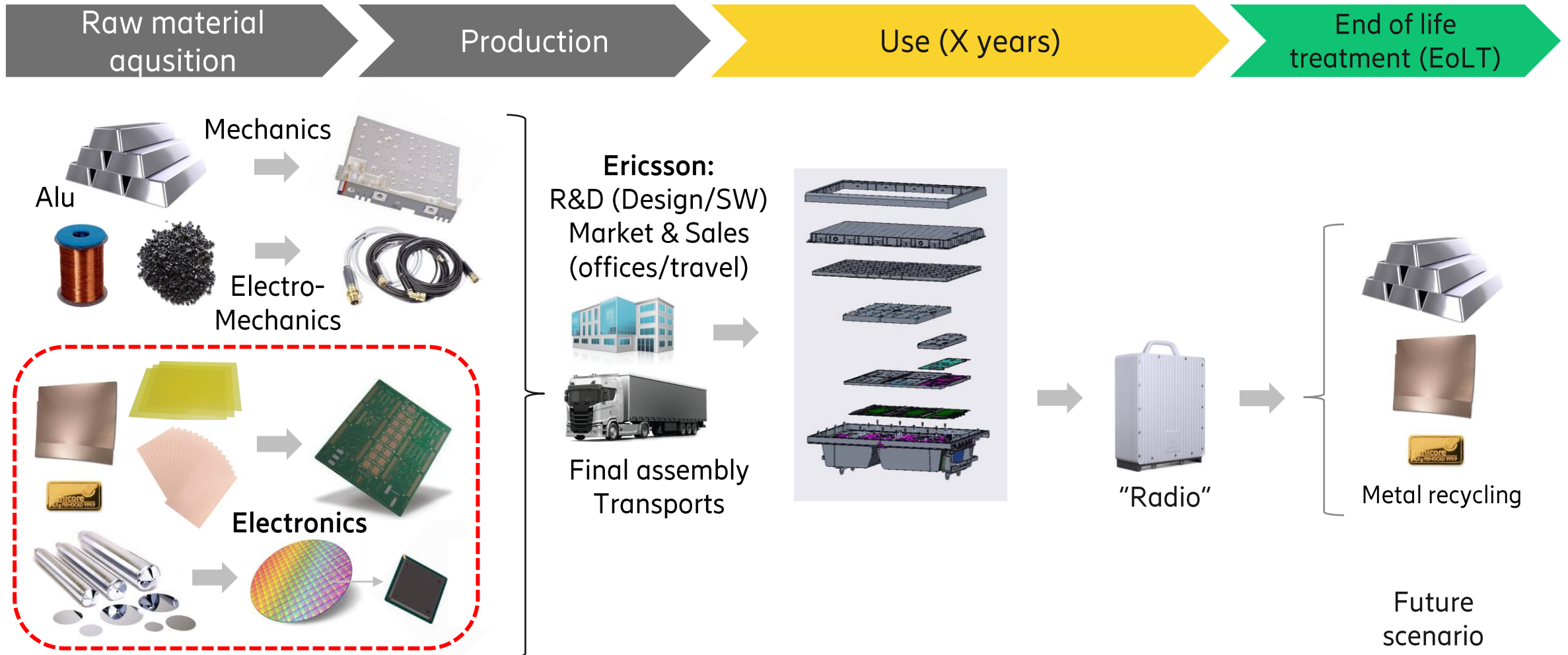


ITU-ETSI Symposium on ICT Sustainability:
Standards Driving Environmental Innovation
11 December 2024

Nina Lövehagen
Ericsson Research



Life Cycle Assessment (LCA)



LCA of an EEE product

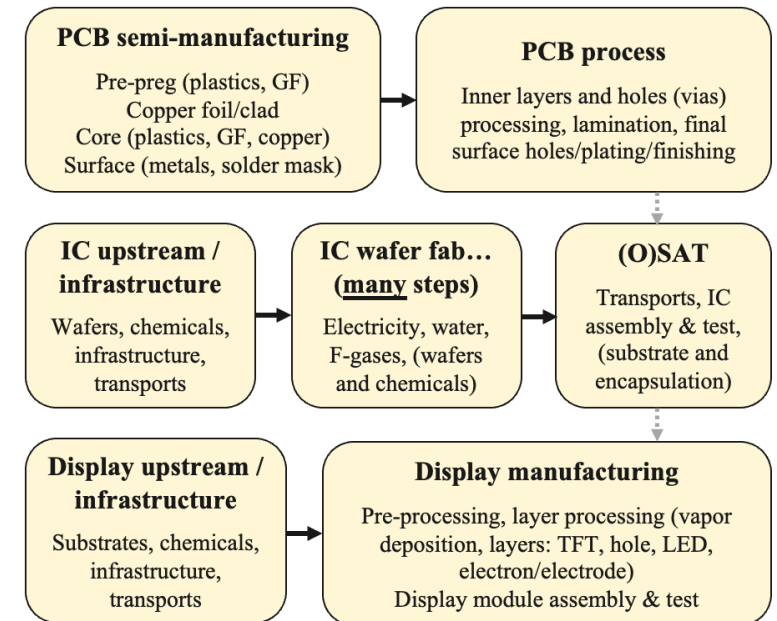
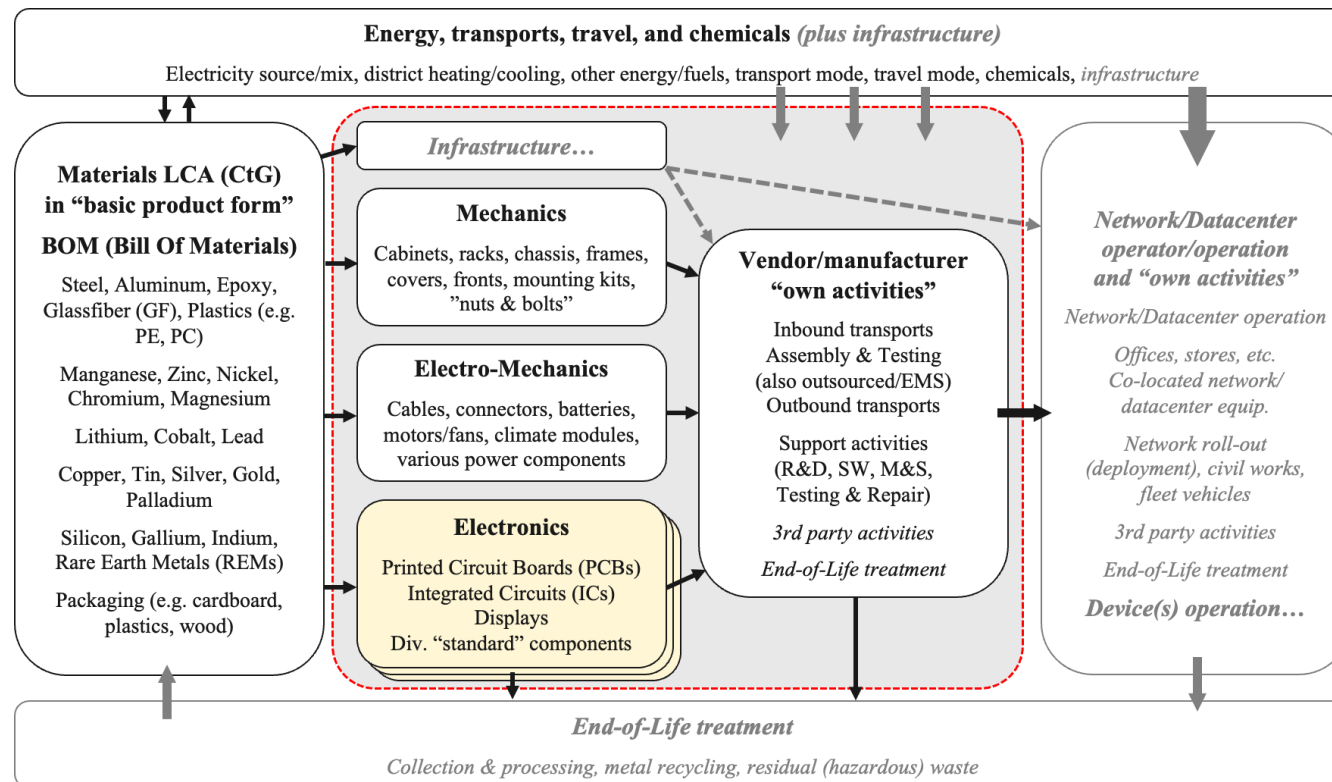
2G–4G RAN Radio



global supply chain,
>>1000 components,
>100 suppliers

2 x 80 W, 18–19 kg, (150 W average)
17 kg aluminum (Al)
0.75 kg plastics/glassfiber
0.6 kg steel (Fe), 0.35 kg copper (Cu)
25 g tin/silver/gold (Sn/Ag/Au)

540 g PCB (9.3 dm²), 5.5–8 cm² IC die area



Simplified LCA methodology



Embodied emissions

- Product parameters, PP
- Factor, f
- Emission factors, EF

Cover life cycle stages: raw material acquisition, production and End-of-life treatment (EoLT)

Use stage emissions

- Annual electricity consumption, AEC
- Active lifetime years, ALY
- Electricity emission factor, EEF

Total lifetime emissions = embodied emissions + use stage emissions

Simplified LCA methodology



Embodied emissions

- Product parameters, PP
- Factor, f
- Emission factors (EF)

Simplified embodied LCA estimate

(requires an existing LCA study to create the EF)

Simplified LCA: Product Parameter Method

(no existing LCA study required, use of existing EFs)

Use stage emissions

- Annual electricity consumption, AEC
- Active lifetime years, ALY
- Electricity emission factor, EEF

$$AEC \times ALY \times EEF$$

Average AEC and ALY for all products over their lifetime
(not counting inactive life years before EoLT)

"The use stage for products that operates using only electricity is typically so simple the equation above covers the basic needs."

Total lifetime emissions = embodied emissions + use stage emissions

Embodied emissions in simplified LCA methodology



Simplified embodied LCA estimate

(requires an existing LCA study to create the EF)

$$PP \times f \times EF$$

PP = weight, volume, size, cost (most common)

f = 1 in most cases

PP (special cases) = % of use or based on cost

If $n > 1$ but < 10 PPs is used, it is still to be considered an embodied LCA estimate where each estimate are just added together

Simplified LCA: Product Parameter Method

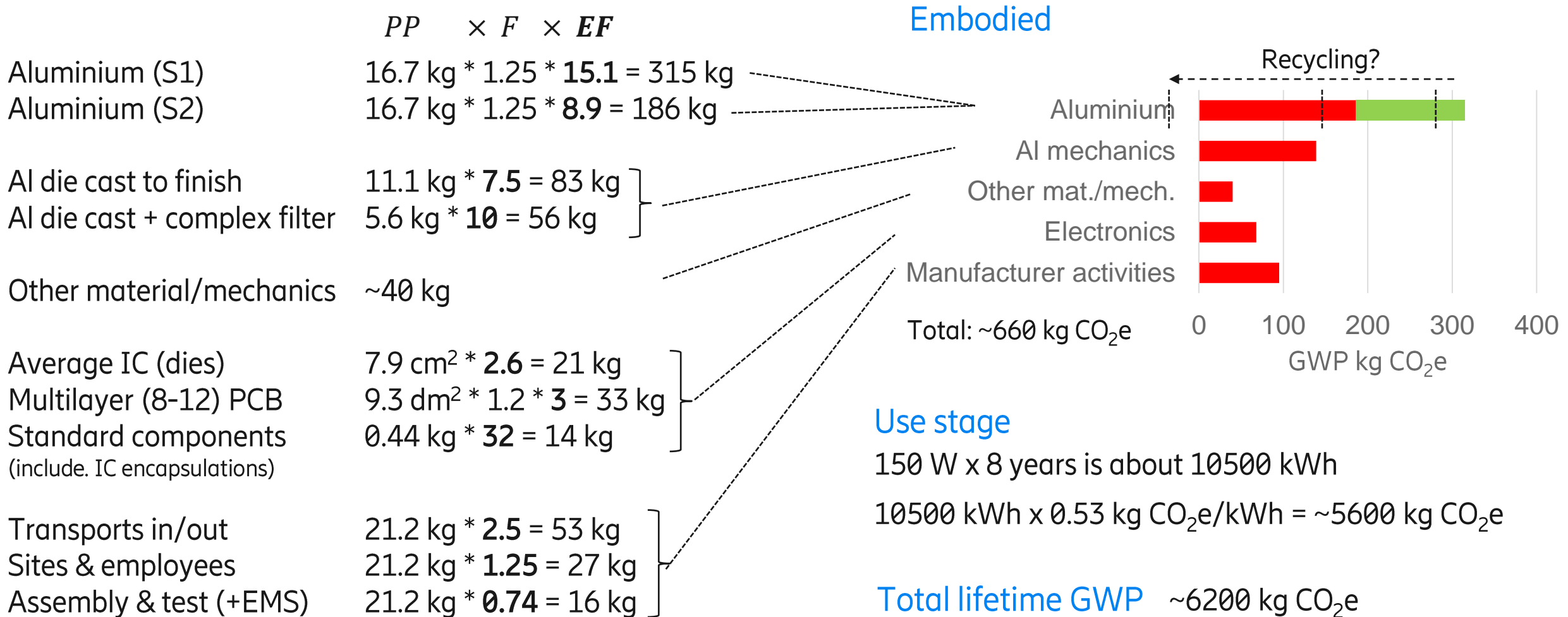
(no existing LCA study required, use existing EFs)

$$\sum_n (PP_n \times f_n \times EF_n)$$

PP = Materials, Processes, Transports, Assembly & Test and end of life treatment (EoLT)

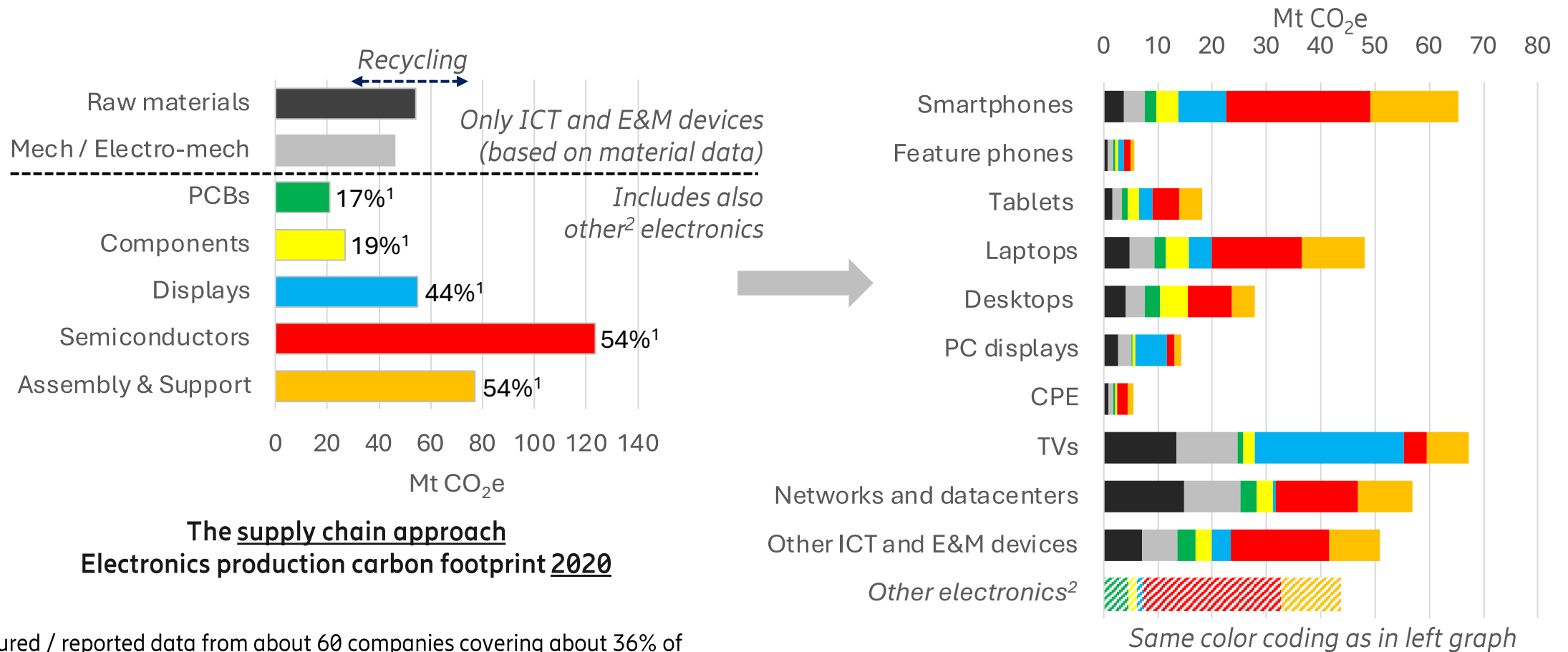
$n \geq 10$ (an exact number cannot be stated)

Product parameter method applied on Radio



Emission factors can be created for any impact category following the same steps

Embodied Carbon Footprint of (ICT) Electronics



¹ Measured / reported data from about 60 companies covering about 36% of total estimated carbon footprint (More companies have been used as references)

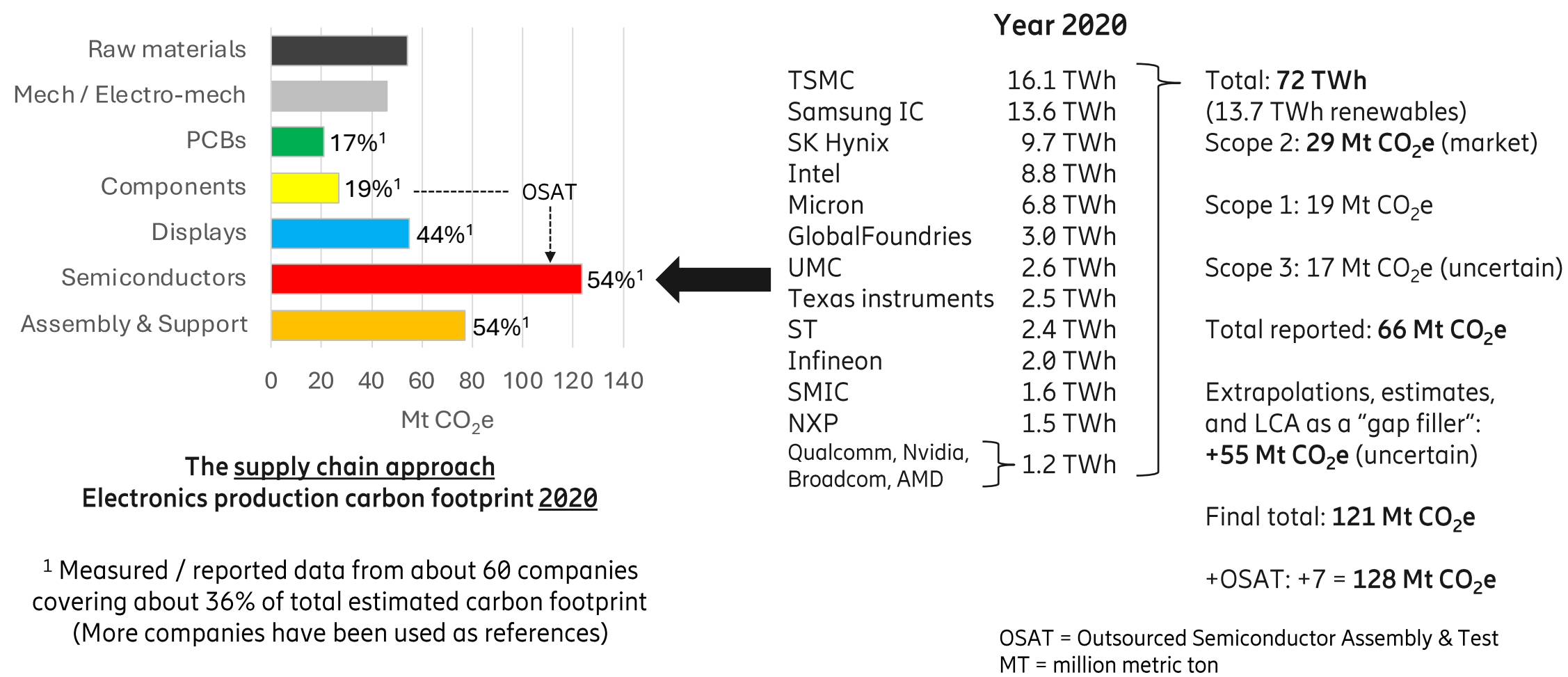
Other ICT and E&M devices: Fixed phones, STBs, Audio devices, Public and commercial displays, Smart meters, Smart home devices, Payment terminals, Surveillance cameras, Others

Other electronics: Appliances / tools, Automotive / aviation, Medical (health care), Industry (production), Government / military

² Not 100% of other electronics (but likely major part). It is the share that "got" included in the ICT and E&M manufacturers total data (as components and assembly/support are for all electronics).

E&M = Entertainment & Media sector
MT = million metric ton

Supply chain approach for semiconductors (ICs)



Key components



	Raw Materials	Processing (scope) Energy, process materials, infrastructure, "overhead"		
ICs	Wafer, process, encapsulation ...materials	Wafers	→ Wafer fab →	IC (O)SAT Low-end: 1.5 kg Memories: 2.2 kg Average: 2.6 kg CO₂e / cm² die area Special types: 4 kg High-end: 5 kg Tech front: 10+ kg
PCBs	Copper, Epoxy, Glass fiber (GF), Silver/Gold	Prepreg, copper foil, CCL, others	→ PCB processing	Basic rigid/flex (1-2 layers): 1 kg Average multilayer (<8 layers): 2.5 kg Average (8-12): 3 kg CO₂e / dm² PCB area Average multilayer (>12 layers): 3.5 kg HDI / IC substrate: 9 kg
Displays	Substrate, film, layer, electrode ...materials	Substrate/layer processing	→ Display assembly & test	TV: 1.85 kg Average: 2.2 kg CO₂e / dm² display area PC display: 2.4 kg Laptop: 3.3 kg Tablet: 4.5 kg Smartphone: 6.8 kg OSAT - Outsourced Semiconductor Assembly & Test HDI - High Density Interconnect

Key challenges

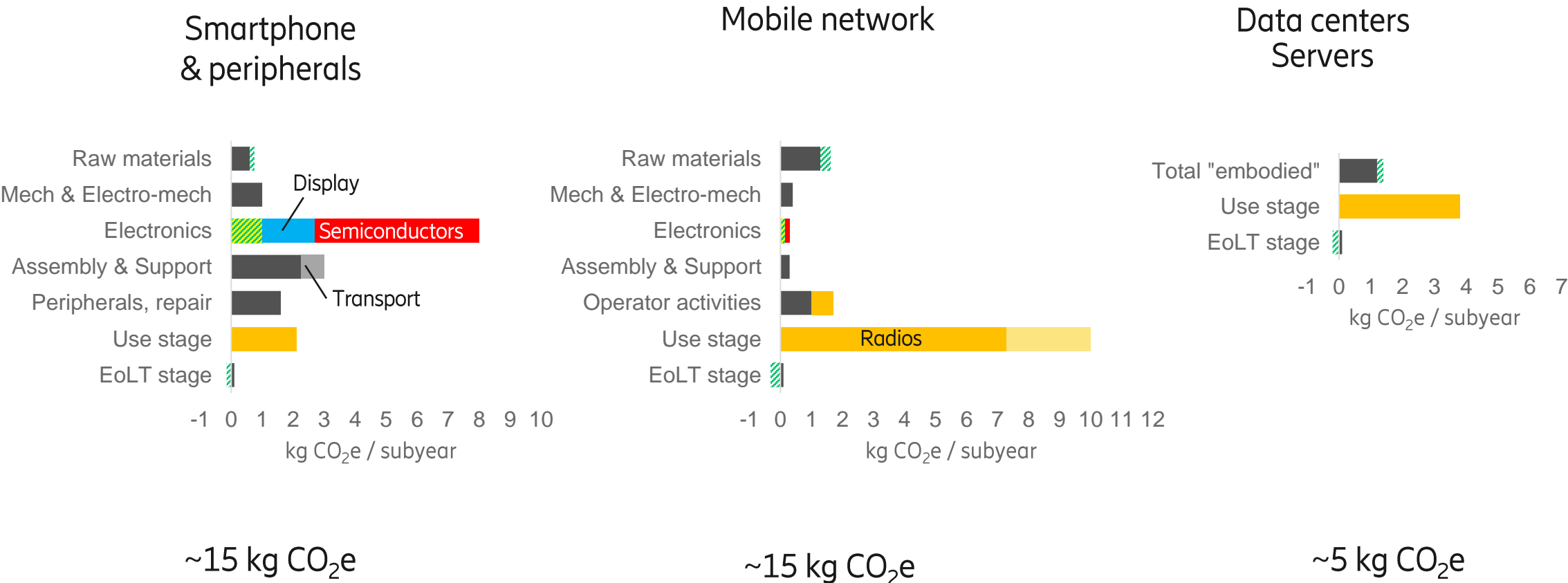


- Choose relevant materials and processes
- Collect emission factors (EF) covering the intended scope
 - Handling of upstream supply chain data
 - Known and unknown data gaps (incl. yield factors, infrastructure)
 - Risk of double accounting or “forgetting...”
 - Quantification of the total product output to be able to create a robust average EF
 - Product output can be sensitive information
 - Allocation of data to various types of components/products
 - Just one average do not work for all components/products

LCA “standard issues”:

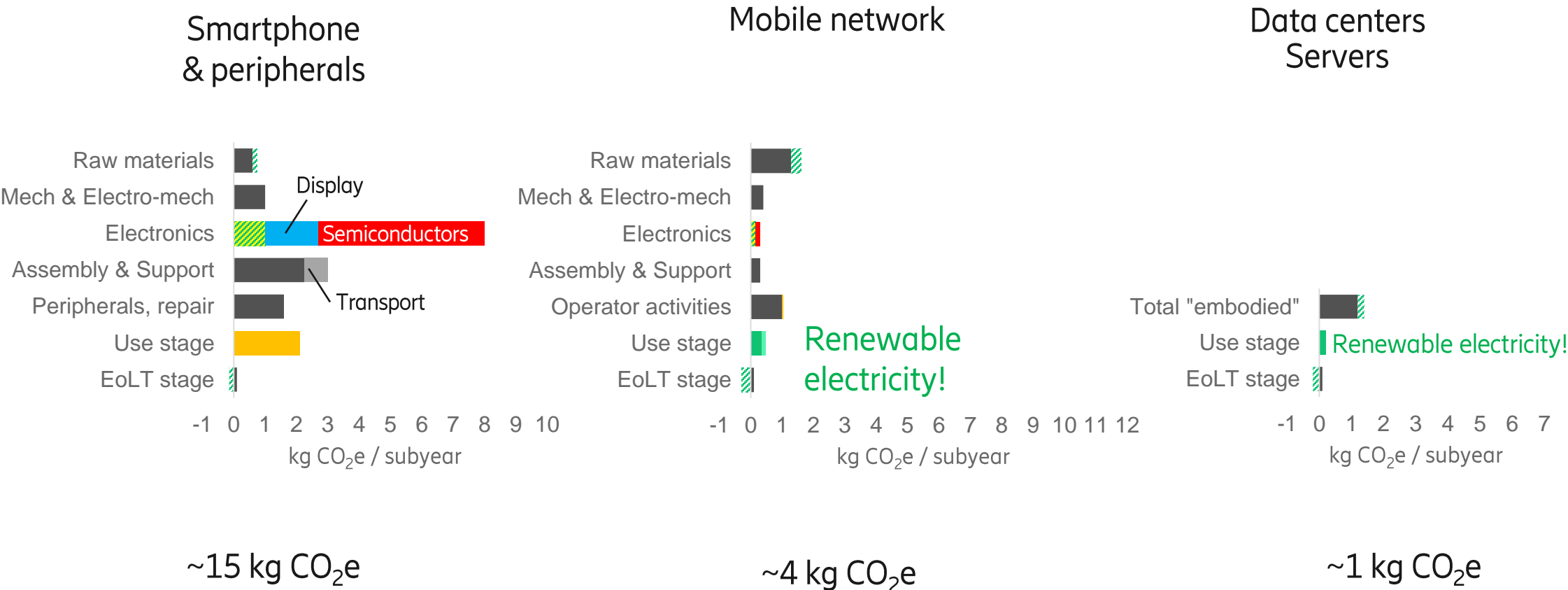
- Old generic data
- Variation in scope
- ...
- ...Uncertainty

Simplified LCA of “a mobile subscription”



Total ~35 kg CO₂e per subyear equals about: ~12 liter fuel

Simplified LCA of “a mobile subscription”

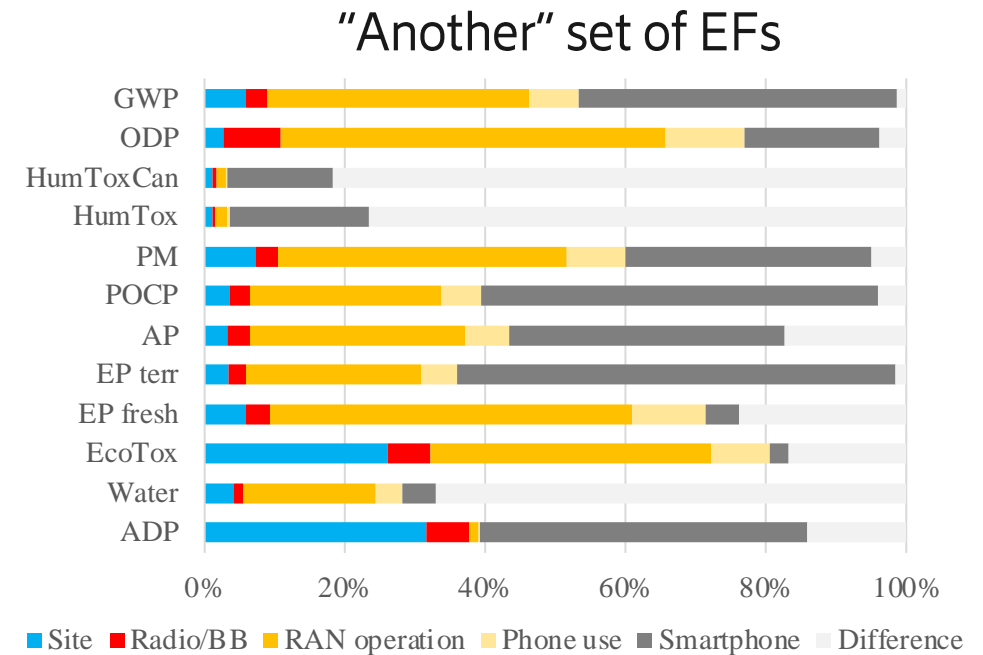
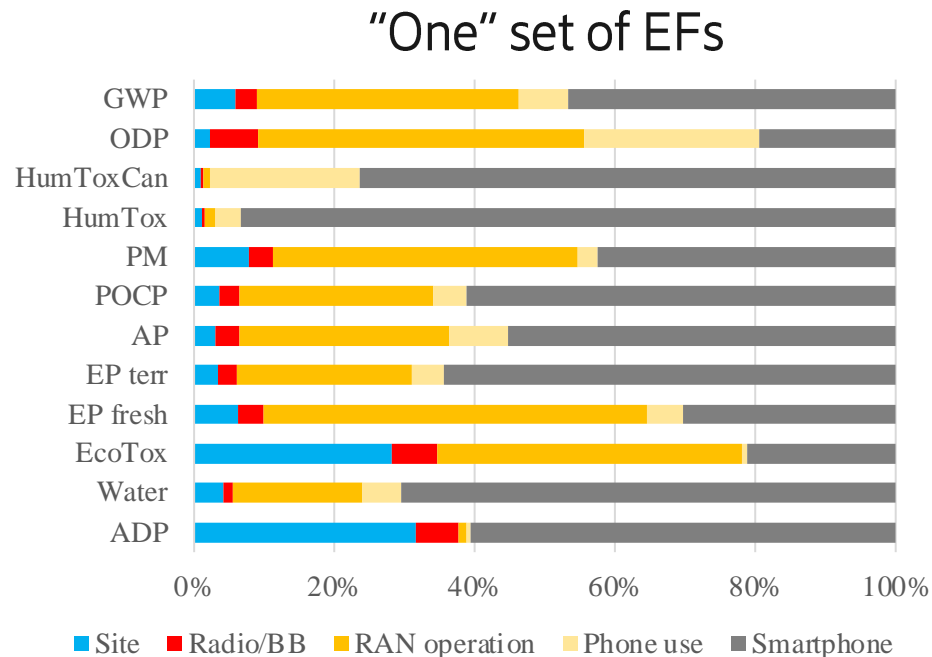


Total ~20 kg CO₂e per subyear equals about: ~7 liter fuel

A lot more impact categories...



Emission factors can be created for any impact category



- 1) Network operation and/or mobile phone (smartphone) manufacturing is key
- 2) Gold and copper (in the phone/smartphone) mining and processing large in Toxicities
- 3) Steel and concrete in site infrastructure is large in a few categories

Material use per subyear

